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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

## 1. Name of conveying party(ies):

Lei Jiang  
Sadasivan Shankar

S-S-03

## 2. Name and address of receiving party(ies)

Name: Intel Corporation

Internal Address: \_\_\_\_\_

Street Address: 2200 Mission College Blvd

City: Santa Clara State: CA Zip: 95052

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

## 3. Nature of conveyance:

- ☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Other \_\_\_\_\_

Execution Date: 04/28/2003

Additional name(s) & address(es) attached? ☐ Yes ☒ No

## 4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: \_\_\_\_\_

A. Patent Application No.(s) 10/340,534

B. Patent No.(s) \_\_\_\_\_

Additional numbers attached? ☐ Yes ☒ No

## 5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Paul J. Fordenbacher

Internal Address: Schwabe Williamson &amp; Wyatt

Suite 1900

Street Address: 1211 SW Fifth Avenue

City: Portland State: OR Zip: 97204

## 6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41).....\$ 40.00

- ☒ Enclosed  
☐ Authorized to be charged to deposit account

## 8. Deposit account number:

500393

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## 9. Signature.

Paul J. Fordenbacher, Reg No. 42,546  
Name of Person Signing  
SignatureApril 28, 2003  
Date

Total number of pages including cover sheet, attachments, and documents: 3

Mail documents to be recorded with required cover sheet information to:  
Commissioner of Patents & Trademarks, Box Assignments  
Washington, D.C. 20231

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**PATENT**  
**REEL: 014038 FRAME: 0600**

No.: P15104-109263-129887

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned, Lei Jiang and Sadasivan Shankar

hereby sell, assign, and transfer to Intel Corporation

a corporation of Delaware, having a principal place of business at

2200 Mission College Blvd., Santa Clara, California 95052, ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all improvements that are disclosed in the application for the United States patent that has been executed by the undersigned prior hereto or concurrently herewith on the dates indicated below and is entitled MINIMIZATION OF MICROELECTRONIC INTERCONNECT THICKNESS VARIATIONS

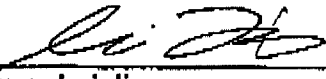
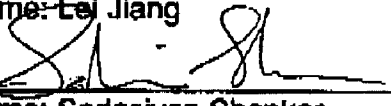
and in and to said application and all divisional applications, continuation applications, continued prosecution applications, continuation-in-part applications, substitute applications, renewal applications, reissue applications, reexaminations, extensions, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original patents, reissued patents, reexamination certificates, and extensions, that have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application;

agree that said Assignee may apply for and receive a patent or patents for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional applications, continuation applications, continued prosecution applications, continuation-in-part applications, substitute applications, renewal applications, reissue applications, reexaminations, extensions and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and representatives all facts known to the undersigned relating to said improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or representatives in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Each Inventor: Please Sign and Date Below:

04/28, 2003  
Date  
28 Apr, 2003  
Date  
\_\_\_\_\_, 20\_\_\_\_  
Date

  
Name: Lei Jiang  
  
Name: Sadasivan Shankar  
\_\_\_\_\_  
Name:

Each Inventor: Please  
also list the date that  
you signed the  
accompanying  
DECLARATION AND  
POWER OF  
ATTORNEY:

04/28, 2003  
Date  
28 Apr, 2003  
Date  
\_\_\_\_\_, 20\_\_\_\_  
Date